Electroninks to Showcase EMI Shielding, iSAP and Backside Metallization at SEMICON India 2026

Company to exhibit with distribution partner Baba Fine Chemicals at booth H4223, Hall 2, spotlighting its metal complex ink portfolio

AUSTIN, TX, UNITED STATES, September 16, 2026 / EINPresswire.com/ -- Electroninks, the leader in metal complex inks for additive manufacturing and advanced semiconductor packaging, today announced its participation in SEMICON India 2026, taking place September 17–19 at the India International Convention & Expo Centre, in New Delhi. Electroninks will exhibit at booth H4223 in Hall 2, co-hosted with distribution partner Baba Fine Chemicals, where the company will showcase its metal complex ink solutions for EMI shielding, integrated semi-additive process (iSAP), and backside metallization (BSM).

Representing Electroninks at the event will be Dhaval Patel, chief financial officer; Brian Liu, APAC sales director; and Takashi Mochizuki, global sales director, who will be on-site throughout the show to meet with customers, partners, and industry stakeholders across India's growing semiconductor and electronics manufacturing ecosystem.

Electroninks will demonstrate its spray-coated MOD (metal organic decomposition) silver inks for EMI shielding,that allows for functional and cost advantages over conventional metallization by delivering immediate metallization and strong sidewall and corner coverage. The inks are engineered for the shielding performance and reliability required in RF modules and advanced packages, while reducing the capital equipment, footprint, and energy costs associated with standard metallization, while also enabling better thermal and 3D metallization for advanced AI chips.

The booth will also feature Electroninks' MOD silver inks for iSAP applications, which enable fine-line redistribution layer (RDL) formation with the conductivity and adhesion needed for advanced packaging. The additive approach allows manufacturers to build conductive seed layers digitally, without the masking and etching steps required in traditional subtractive processes.

Additionally, Electroninks will showcase its spray-deposited MOD silver ink for backside metallization, developed to support metal-based thermal interface material (TIM) integration in RF module and logic device packaging. The ink forms a dense, highly conductive film with the adhesion and reliability performance needed for stable metallurgical bonding, offering manufacturers a scalable, atmospheric-pressure for wafer and larger panel applications.

"India represents one of the fastest-growing semiconductor manufacturing bases in the world, and our partnership with Baba Fine Chemicals puts Electroninks directly alongside the customers building that capacity," said Takashi Mochizuki, global sales director at Electroninks. "Whether it's EMI shielding, iSAP, or backside metallization, the throughline is the same: manufacturers here are looking for materials that can scale with them, and that's exactly what our ink portfolio is built to do."

SEMICON India 2026 is the country's premier semiconductor conference and exhibition, jointly organized by the India Semiconductor Mission, the Ministry of Electronics and Information Technology, and SEMI. Electroninks' co-hosted presence with Baba Fine Chemicals reflects the company's continued investment in India's semiconductor ecosystem as the country builds out its domestic manufacturing, packaging, and materials supply chain.

Attendees are invited to visit Electroninks at booth H4223 in Hall 2 to see live demonstrations of its ink portfolio and to discuss how additive metallization can be integrated into existing manufacturing lines.

For more information on Electroninks products and solutions, please visit www.electroninks.com.

About Electroninks

Electroninks Incorporated is a world-leader in the commercialization of advanced materials for electronics and semiconductor packaging. We have developed a full suite of proprietary metal complex conductive ink solutions and complementary material sets, thus accelerating time to market for both new innovations and drop-in manufacturing breakthroughs.

Electroninks’ metal complex inks – including silver, gold, platinum, nickel and copper – deliver higher conductivity, manufacturing flexibility, and cost-effectiveness. The company’s conductive inks provide reliable solutions for applications in printed circuit board (PCB) manufacturing, semiconductor packaging, consumer electronics, wearables, medical devices and more. We also partner closely with best-in-class equipment and integration partners to provide customers with a total ink and process solution with the ultimate goal of reducing the manufacturing costs and complexity.

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